

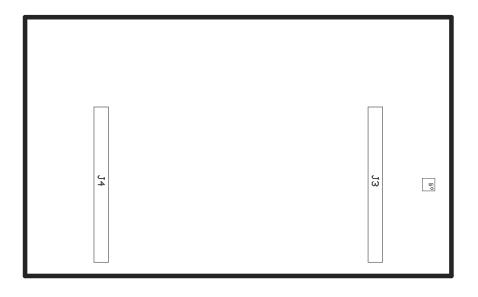
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01539 REV: E2	SVN REV: Not In VersionControl	
	TID #: 01539		
PLOT NAME = Top Assembly Drawing	GENERATED : 4/26/2018 4:38:33	PM TEXAS INSTRUMENTS	

outputs

outputs



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01539 REV	V: E2 SVN REV	: Not In VersionControl
	TID #: 01539		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/26/2018	4:38:35 PM	TEXAS INSTRUMENTS

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